

6-Pin DIP Low Input Current Phototransistor Optocouplers

MCT5210M, MCT5211M

Description

The MCT5210M and MCT5211M devices consist of a high-efficiency AlGaAs infrared emitting diode coupled with an NPN phototransistor in a six-pin dual-in-line package.

The devices are well suited for CMOS to LSTT/TTL interfaces, offering 250% CTR CE(SAT) with 1 mA of LED input current. With an LED input current of 1.6 mA, data rates to 20 kbits/s are possible.

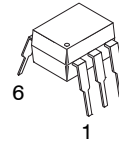
Both can easily interface LSTTL to LSTTL/TTL, and with use of an external base-to-emitter resistor data rates of 100 kbits/s can be achieved.

Features

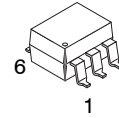
- High CTR_{CE(SAT)} Comparable to Darlington
- High Common Mode Transient Rejection: 5 kV/μs
- Data Rates Up to 150 kbits/s (NRZ)
- Safety and Regulatory Approvals:
 - UL1577; 4,170 VAC_{RMS} for 1 Minute
 - DIN-EN/IEC60747-5-5, 850 V Peak Working Insulation Voltage
- These are Pb-Free Devices

Applications

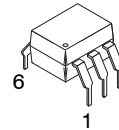
- CMOS to CMOS/LSTTL Logic Isolation
- LSTTL to CMOS/LSTTL Logic Isolation
- RS-232 Line Receiver
- Telephone Ring Detector
- AC Line Voltage Sensing
- Switching Power Supply



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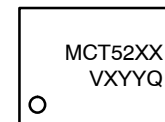


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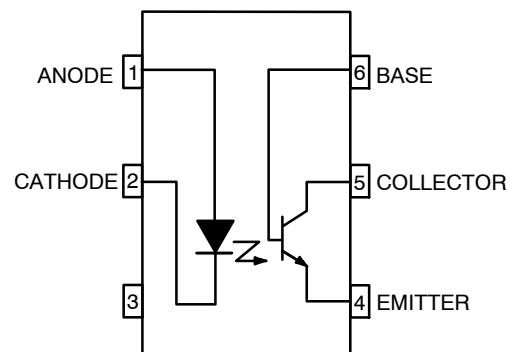
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MARKING DIAGRAM



- MCT52XX = Device Number
 XX = 10, 11
 V = DIN EN/IEC60747-5-5 Option (only appears on component ordered with this option)
 X = One-Digit Year Code, e.g., '5'
 YY = Digit Work Week, Ranging from '01' to '53'
 Q = Assembly Package Code

SCHEMATIC



ORDERING INFORMATION

See detailed ordering and shipping information on page 16 of this data sheet.

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SAFETY AND INSULATION RATINGS (As per DIN EN/IEC 60747-5-5, this optocoupler is suitable for “safe electrical insulation” only within the safety limit data. Compliance with the safety ratings shall be ensured by means of protective circuits.)

Parameter		Characteristics
Installation Classifications per DIN VDE 0110/1.89 Table 1, For Rated Mains Voltage	<150 V _{RMS}	I–IV
	<300 V _{RMS}	I–IV
Climatic Classification		55/100/21
Pollution Degree (DIN VDE 0110/1.89)		2
Comparative Tracking Index		175

Symbol	Parameter	Value	Unit
V _{PR}	Input-to-Output Test Voltage, Method A, V _{IORM} × 1.6 = V _{PR} , Type and Sample Test with t _m = 10 s, Partial Discharge < 5 pC	1360	V _{peak}
	Input-to-Output Test Voltage, Method B, V _{IORM} × 1.875 = V _{PR} , 100% Production Test with t _m = 1 s, Partial Discharge < 5 pC	1594	V _{peak}
V _{IORM}	Maximum Working Insulation Voltage	850	V _{peak}
V _{IOTM}	Highest Allowable Over-Voltage	6000	V _{peak}
	External Creepage	≥7	mm
	External Clearance	≥7	mm
	External Clearance (for Option TV, 0.4" Lead Spacing)	≥10	mm
DTI	Distance Through Insulation (Insulation Thickness)	≥0.5	mm
T _S	Case Temperature (Note 1)	175	°C
I _{S, INPUT}	Input Current (Note 1)	350	mA
P _{S, OUTPUT}	Output Power (Note 1)	800	mW
R _{IO}	Insulation Resistance at T _S , V _{IO} = 500 V (Note 1)	>10 ⁹	Ω

1. Safety limit values – maximum values allowed in the event of a failure.

ABSOLUTE MAXIMUM RATINGS (T_A = 25°C unless otherwise noted)

Symbol	Parameter	Value	Unit
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TOTAL DEVICE

T _{STG}	Storage Temperature	–40 to +125	°C
T _{OPR}	Operating Temperature	–40 to +100	°C
T _J	Junction Temperature	–40 to +125	°C
T _{SOL}	Lead Solder Temperature	260 for 10 seconds	°C
P _D	Total Device Power Dissipation @ 25°C (LED plus detector)	225	mW
	Derate Linearly from 25°C	3.5	mW/°C

EMITTER

I _F	Continuous Forward Current	50	mA
V _R	Reverse Input Voltage	6	V
I _{F(pk)}	Forward Current – Peak (1 μs pulse, 300 pps)	3.0	A
P _D	LED Power Dissipation at 25°C	75	mW
	Derate Linearly from 25°C	1.0	mW/°C

DETECTOR

I _C	Continuous Collector Current	150	mA
P _D	Detector Power Dissipation @ 25°C	150	mW
	Derate Linearly from 25°C	2.0	mW/°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

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ELECTRICAL CHARACTERISTICS (T_A = 25°C, unless otherwise noted)

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
INDIVIDUAL COMPONENT CHARACTERISTICS						
EMITTER						
V _F	Input Forward Voltage	I _F = 5 mA	–	1.25	1.50	V
$\frac{\Delta V_F}{\Delta T_A}$	Forward Voltage Temperature Coefficient	I _F = 2 mA	–	–1.75	–	mV/°C
V _R	Reverse Voltage	I _R = 10 μA	6	–	–	V
C _J	Junction Capacitance	V _F = 0 V, f = 1.0 MHz	–	18	–	pF
DETECTOR						
BV _{CEO}	Breakdown Voltage Collector-to-Emitter	I _C = 1.0 mA, I _F = 0	30	100	–	V
BV _{CBO}	Breakdown Voltage Collector-to-Base	I _C = 10 μA, I _F = 0	30	120	–	V
BV _{EBO}	Breakdown Voltage Emitter-to-Base	I _E = 10 μA, I _F = 0	5	10	–	V
I _{CER}	Dark Current, Collector-to-Emitter	V _{CE} = 10 V, I _F = 0, R _{BE} = 1 MΩ	–	1	100	nA
C _{CE}	Capacitance, Collector-to-Emitter	V _{CE} = 0 V, f = 1 MHz	–	10	–	pF
C _{CB}	Capacitance, Collector-to-Base	V _{CB} = 0 V, f = 1 MHz	–	80	–	pF
C _{EB}	Capacitance, Emitter-to-Base	V _{EB} = 0 V, f = 1 MHz	–	15	–	pF

ELECTRICAL CHARACTERISTICS (T_A = 25°C, unless otherwise noted) (continued)

Symbol	Parameter	Test Conditions	Device	Min	Typ	Max	Unit
TRANSFER CHARACTERISTICS							
DC CHARACTERISTICS							
CTR _{CE(SAT)}	Saturated Current Transfer Ratio Collector-to-Emitter (Note 2)	I _F = 3.0 mA, V _{CE} = 0.4 V	MCT5210M	60	–	–	%
		I _F = 1.6 mA, V _{CE} = 0.4 V	MCT5211M	100	–	–	%
		I _F = 1.0 mA, V _{CE} = 0.4 V		75	–	–	%
CTR _(CE)	Current Transfer Ratio Collector-to-Emitter (Note 2)	I _F = 3.0 mA, V _{CE} = 5.0 V	MCT5210M	70	–	–	%
		I _F = 1.6 mA, V _{CE} = 5.0 V	MCT5211M	150	–	–	%
		I _F = 1.0 mA, V _{CE} = 5.0 V		110	–	–	%
CTR _(CB)	Current Transfer Ratio Collector-to-Base (Note 3)	I _F = 3.0 mA, V _{CE} = 4.3 V	MCT5210M	0.2	–	–	%
		I _F = 1.6 mA, V _{CE} = 4.3 V	MCT5211M	0.3	–	–	%
		I _F = 1.0 mA, V _{CE} = 4.3 V		0.25	–	–	%
V _{CE(SAT)}	Saturation Voltage	I _F = 3.0 mA, I _{CE} = 1.8 mA	MCT5210M	–	–	0.4	V
		I _F = 1.6 mA, I _{CE} = 1.6 mA	MCT5211M	–	–	0.4	V

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ELECTRICAL CHARACTERISTICS (T_A = 25°C, unless otherwise noted) (continued)

Symbol	Parameter	Test Conditions		Device	Min	Typ	Max	Unit
TRANSFER CHARACTERISTICS								
AC CHARACTERISTICS								
T _{PHL}	Propagation Delay HIGH-to-LOW (Note 4)	R _L = 330 Ω, R _{BE} = ∞	I _F = 3.0 mA, V _{CC} = 5.0 V	MCT5210M	–	10	–	μs
		R _L = 3.3 kΩ, R _{BE} = 39 kΩ			–	7	–	μs
		R _L = 750 Ω, R _{BE} = ∞	I _F = 1.6 mA, V _{CC} = 5.0 V	MCT5211M	–	14	–	μs
		R _L = 4.7 kΩ, R _{BE} = 91 kΩ			–	15	–	μs
		R _L = 1.5 kΩ, R _{BE} = ∞			–	17	–	μs
		R _L = 10 kΩ, R _{BE} = 160 kΩ			–	24	–	μs
T _{PLH}	Propagation Delay LOW-to-HIGH (Note 5)	R _L = 330 Ω, R _{BE} = ∞	I _F = 3.0 mA, V _{CC} = 5.0 V	MCT5210M	–	0.4	–	μs
		R _L = 3.3 kΩ, R _{BE} = 39 kΩ			–	8	–	μs
		R _L = 750 Ω, R _{BE} = ∞	I _F = 1.6 mA, V _{CC} = 5.0 V	MCT5211M	–	2.5	–	μs
		R _L = 4.7 kΩ, R _{BE} = 91 kΩ			–	11	–	μs
		R _L = 1.5 kΩ, R _{BE} = ∞			–	7	–	μs
		R _L = 10 kΩ, R _{BE} = 160 kΩ			–	16	–	μs

ELECTRICAL CHARACTERISTICS (T_A = 25°C, unless otherwise noted) (continued)

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
ISOLATION CHARACTERISTICS						
V _{ISO}	Input-Output Isolation Voltage (Note 6)	t = 1 Minute	4170	–	–	VAC _{RMS}
R _{ISO}	Isolation Resistance (Note 6)	V _{I-O} = ±500 VDC, T _A = 25°C	10 ¹¹	–	–	Ω
C _{ISO}	Isolation Capacitance (Note 7)	V _{I-O} = 0 V, f = 1 MHz	–	0.4	0.6	pF
CM _H	Common Mode Transient Rejection – Output HIGH	V _{CM} = 50 V _{P-P} , R _L = 750 Ω, I _F = 0	–	5000	–	V/μs
CM _L	Common Mode Transient Rejection – Output LOW	V _{CM} = 50 V _{P-P} , R _L = 750 Ω, I _F = 1.6 mA	–	5000	–	V/μs

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

- DC Current Transfer Ratio (CTR_{CE}) is defined as the transistor collector current (I_{CE}) divided by the input LED current (I_F) x 100%, at a specified voltage between the collector and emitter (V_{CE}).
- The collector base Current Transfer Ratio (CTR_{CB}) is defined as the transistor collector base photocurrent (I_{CB}) divided by the input LED current (I_F) time 100%.
- Referring to Figure 16 the T_{PHL} propagation delay is measured from the 50% point of the rising edge of the data input pulse to the 1.3 V point on the falling edge of the output pulse.
- Referring to Figure 16 the T_{PLH} propagation delay is measured from the 50% point of the falling edge of data input pulse to the 1.3 V point on the rising edge of the output pulse.
- Device considered a two terminal device: pins 1, 2, and 3 shorted together and pins 5, 6 and 7 are shorted together.
- C_{ISO} is the capacitance between the input (pins 1, 2, 3 connected) and the output (pin 4, 5, 6 connected).

TYPICAL PERFORMANCE CURVES

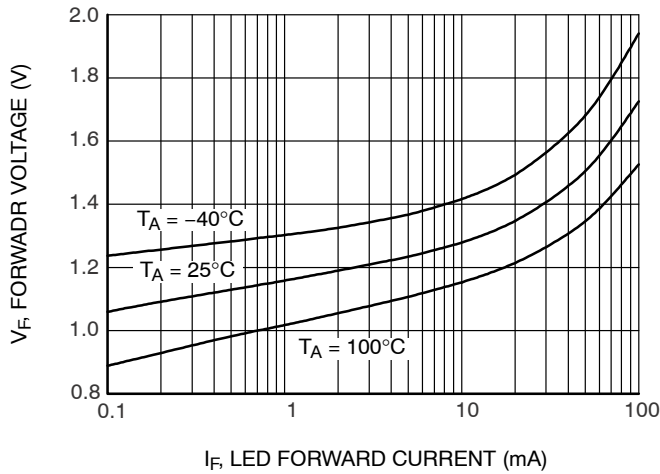


Figure 1. LED Forward Voltage vs. Forward Current

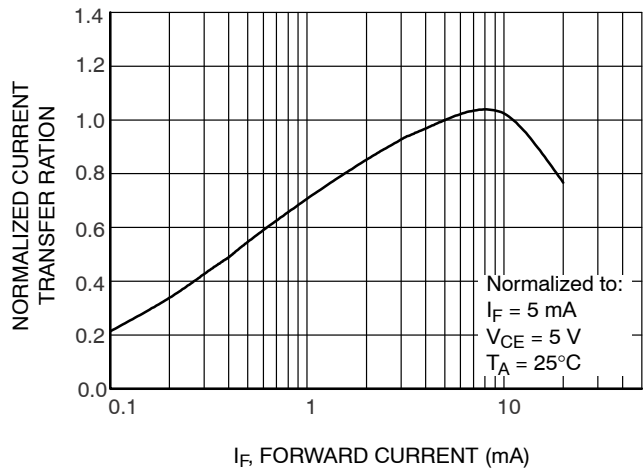


Figure 2. Normalized Current Transfer Ratio vs. Forward Current

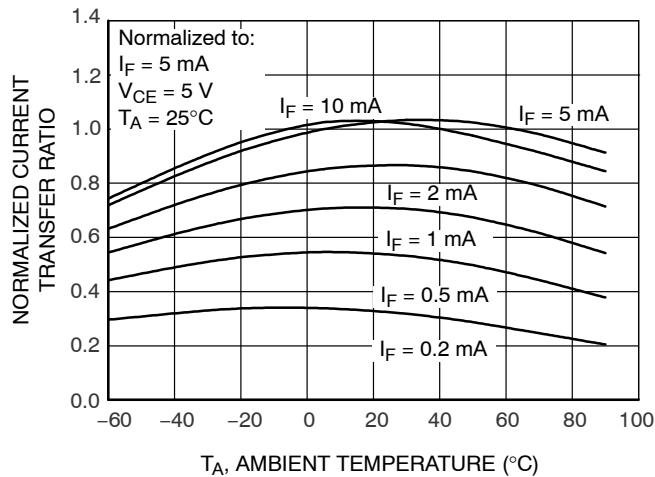


Figure 3. Normalized CTR vs. Temperature

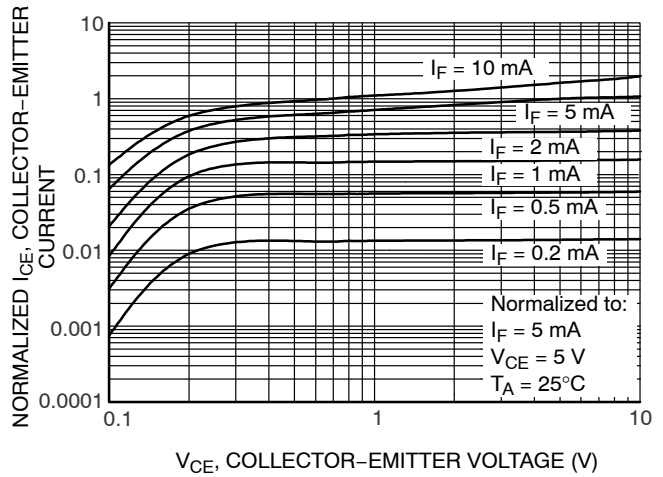


Figure 4. Normalized Collector vs. Collector-Emitter Voltage

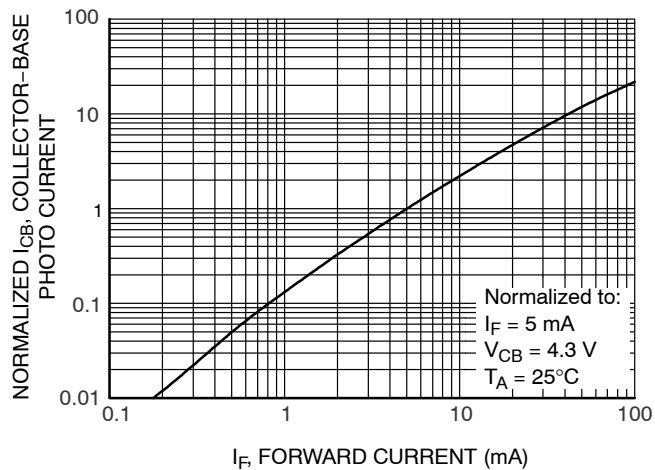


Figure 5. Normalized Collector Base Photocurrent Ratio vs. Forward Current

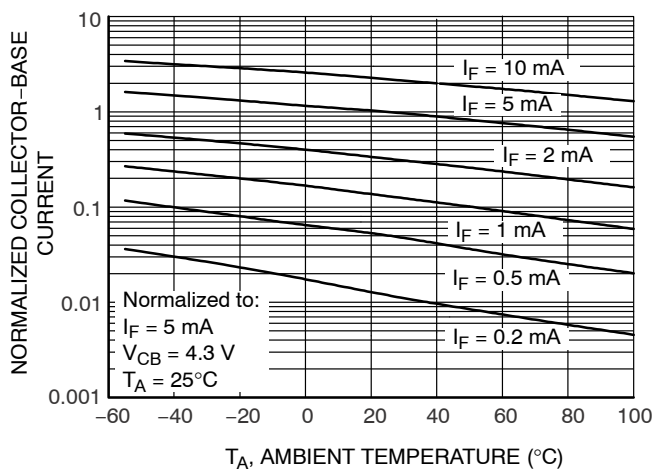


Figure 6. Normalized Collector-Base Current vs. Temperature

TYPICAL PERFORMANCE CURVES (continued)

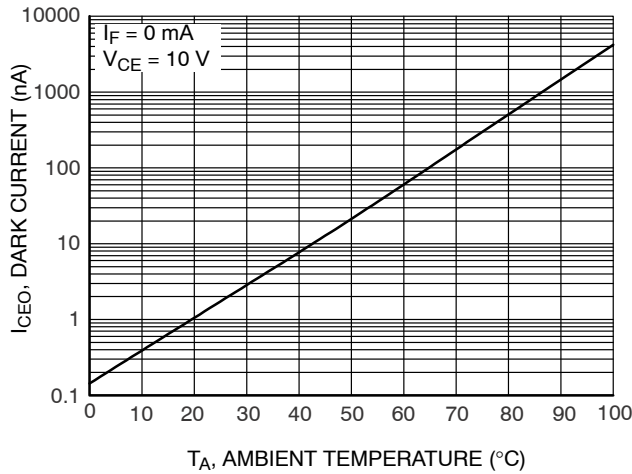


Figure 7. Collector-Emitter Dark Current vs. Ambient Temperature

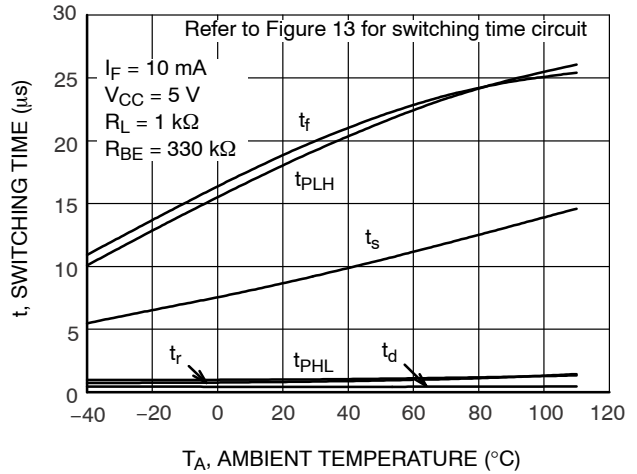


Figure 8. Switching Time vs. Ambient Temperature

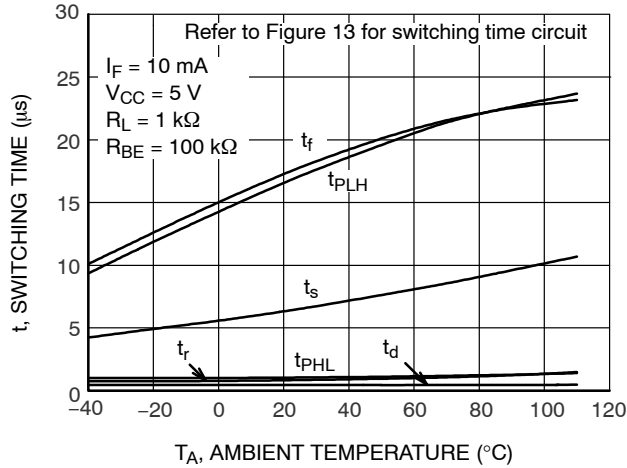


Figure 9. Switching Time vs. Ambient Temperature

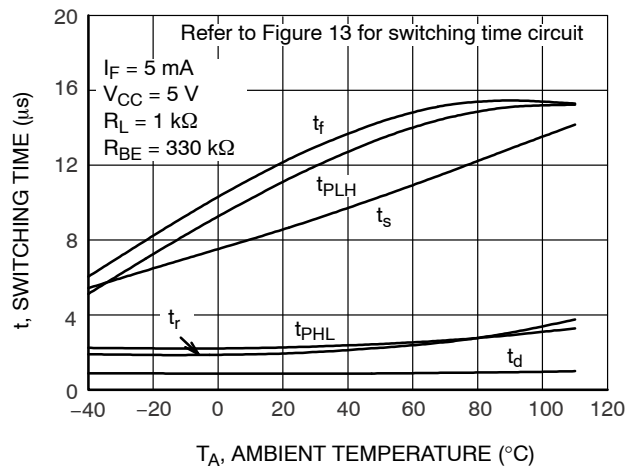


Figure 10. Switching Time vs. Ambient Temperature

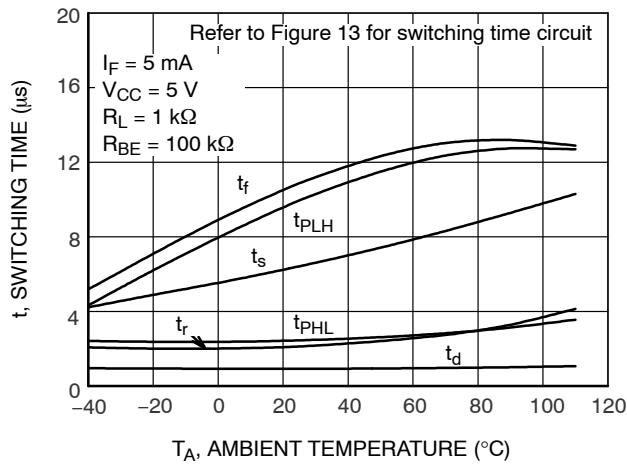


Figure 11. Switching Time vs. Ambient Temperature

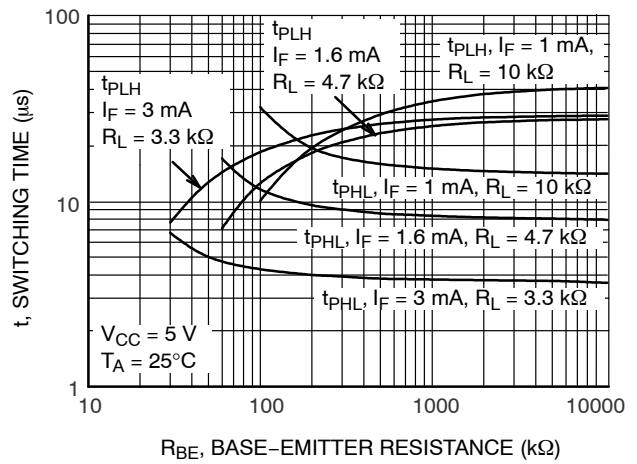


Figure 12. Switching Time vs. Base-Emitter Resistance

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SWITCHING TIME TEST CIRCUIT AND WAVEFORMS

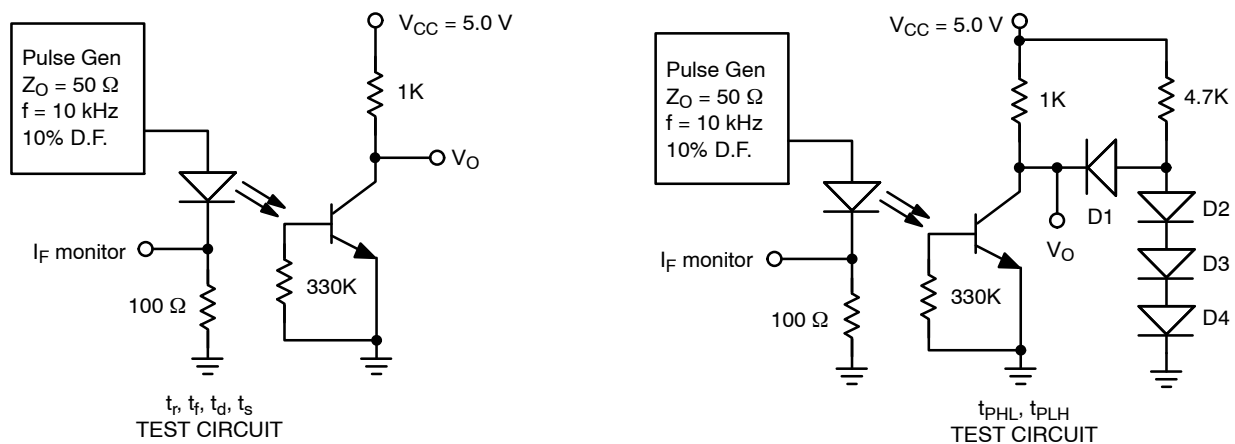


Figure 13. Switching Time Test Circuit

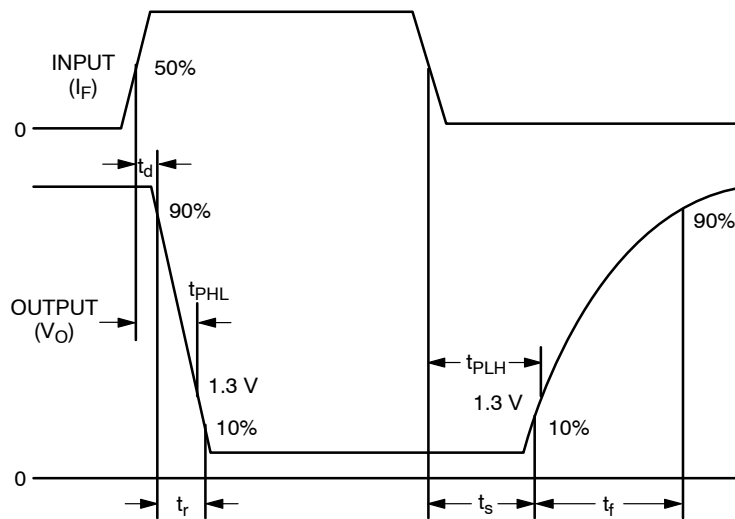


Figure 14. Switching Time Test Circuit

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REFLOW PROFILE

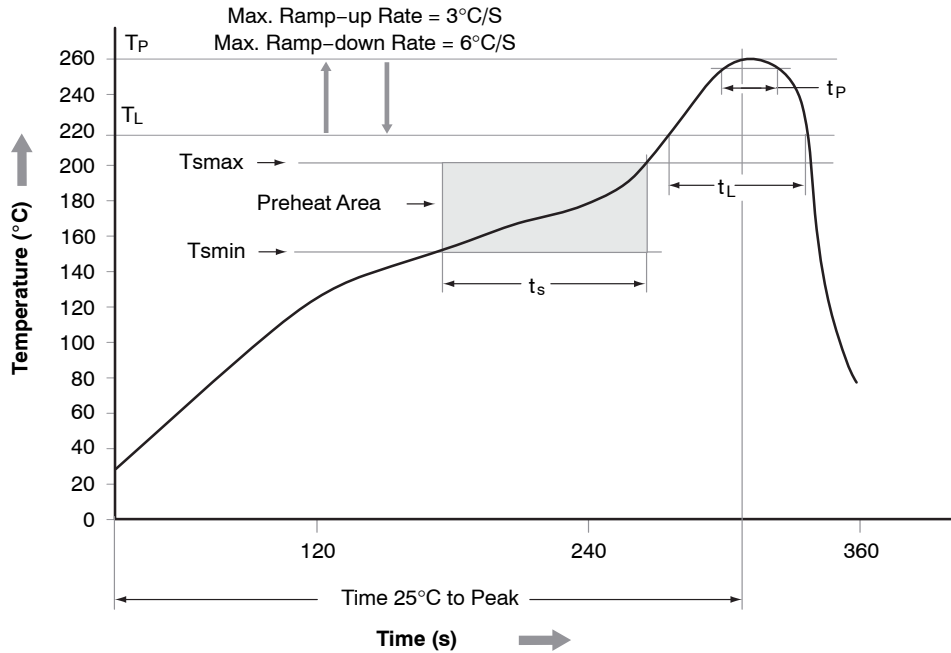


Figure 15. Reflow Profile

Table 1.

Profile Feature	Pb-Free Assembly Profile
Temperature Minimum (T_{sm})	150°C
Temperature Maximum (T_{sp})	260°C
Time (t_s) from (T_{sm} to T_{sp})	60 – 120 seconds
Ramp-up Rate (t_L to t_p)	3°C/second maximum
Liquidous Temperature (T_L)	217°C
Time (t_L) Maintained Above (T_L)	60 – 150 seconds
Peak Body Package Temperature	260°C +0°C / -5°C
Time (t_p) within 5°C of 260°C	30 seconds
Ramp-down Rate (T_P to T_L)	6°C/second maximum
Time 25°C to Peak Temperature	8 minutes maximum

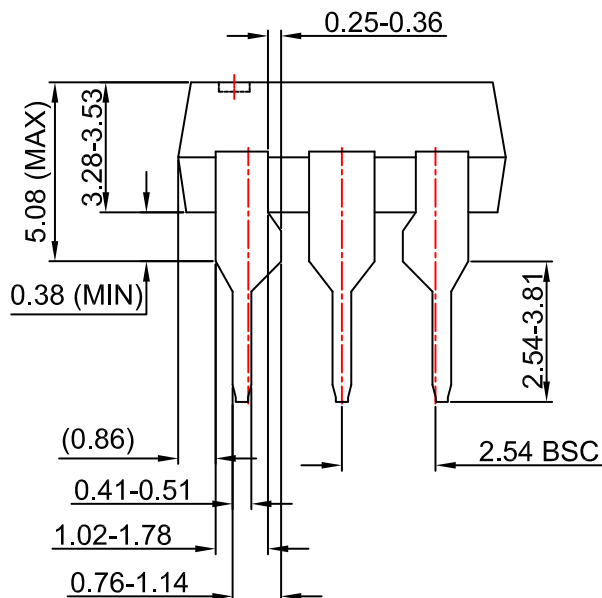
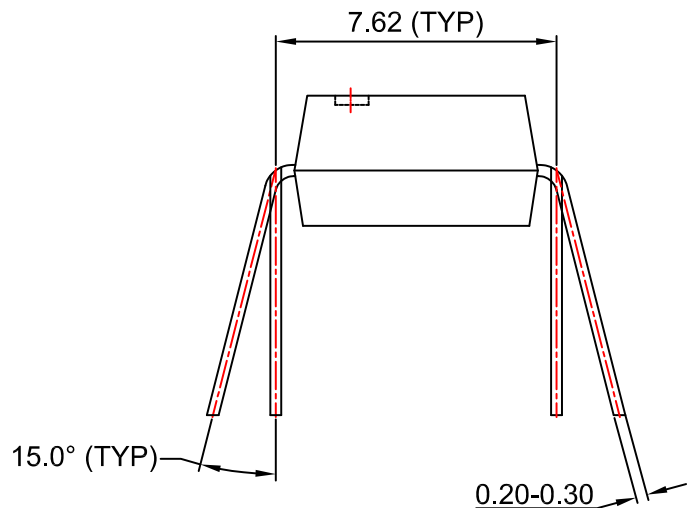
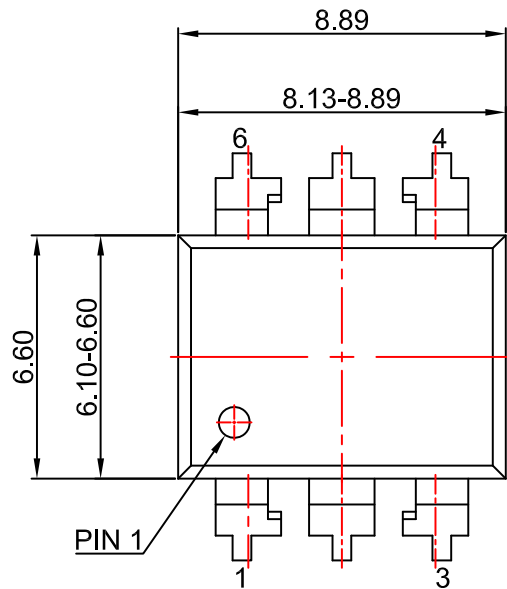
ORDERING INFORMATION (Note 8)

Part Number	Package	Packing Method
MCT5210M	DIP 6-Pin	Tube (50 Units)
MCT5210SM	SMT 6-Pin (Lead Bend)	Tube (50 Units)
MCT5210SR2M	SMT 6-Pin (Lead Bend)	Tape and Reel (1000 Units)
MCT5210VM	DIP 6-Pin, DIN EN/IEC60747-5-5 Option	Tube (50 Units)
MCT5210SVM	SMT 6-Pin (Lead Bend), DIN EN/IEC60747-5-5 Option	Tube (50 Units)
MCT5210SR2VM	SMT 6-Pin (Lead Bend), DIN EN/IEC60747-5-5 Option	Tape and Reel (1000 Units)
MCT5210TVM	DIP 6-Pin, 0.4" Lead Spacing, DIN EN/IEC60747-5-5 Option	Tube (50 Units)

8. The product orderable part number system listed in this table also applies to the MCT5211M device.

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NOTES:

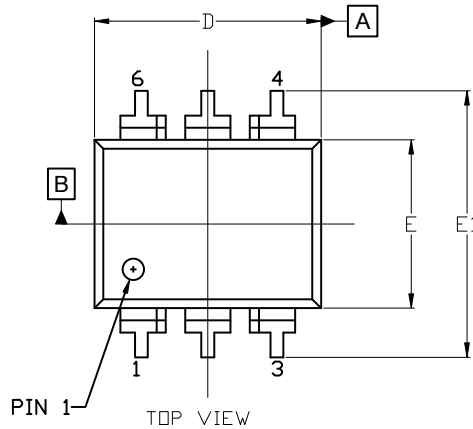
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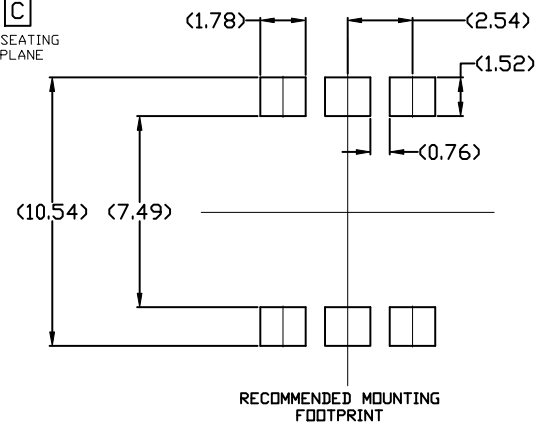
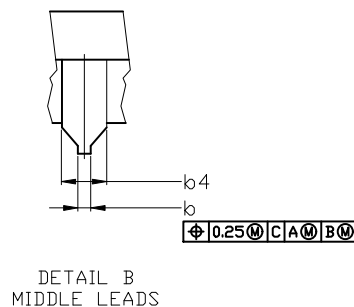
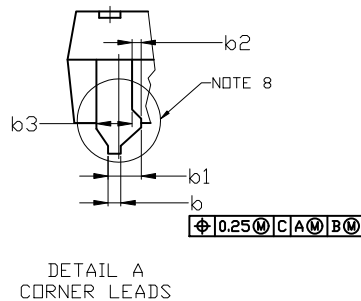
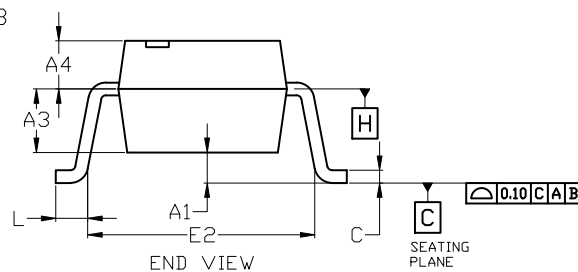
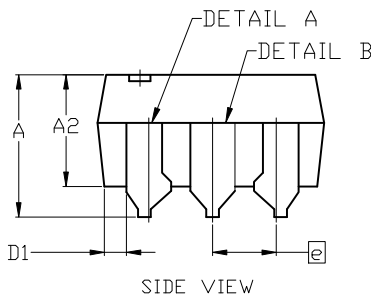
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CASE 646BY
ISSUE A

DATE 15 JUL 2019


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSIONS A, A1, AND L ARE MEASURED WITH THE PACKAGE SEATED.
4. DIMENSIONS D, D1, AND E1 DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS. MOLD FLASH OR PROTRUSIONS ARE NOT TO EXCEED 2.54mm.
5. PACKAGE CONTOUR IS OPTIONAL (ROUNDED OR SQUARE CORNERS).
6. CENTER LINE OF CORNER LEADS IS LOCATED BY LOCATING THE CENTER OF FEATURE b2 AND b3.

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	---	---	4.80
A1	0.38	---	---
A2	3.28	3.40	3.53
A3	2.49 REF		
A4	1.89 REF		
b	0.41	0.46	0.51
b1	0.76	0.92	1.14
b2	0.25	0.28	0.36
b3	1.02	1.40	1.78
b4	1.778 REF		
c	0.20	0.25	0.30
D	8.13	8.51	8.89
D1	0.86 REF		
E	6.10	6.35	6.60
E1	8.43	9.17	9.90
E2	8.13 REF		
e	2.54 BSC		
L	0.16	0.52	0.88



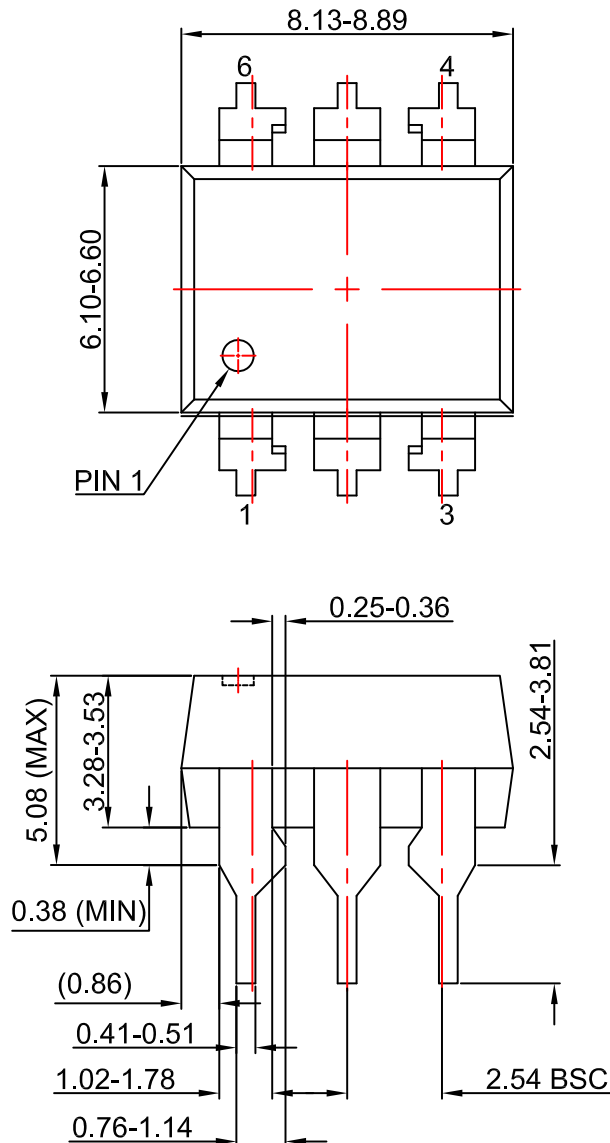
For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERM/D.

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